

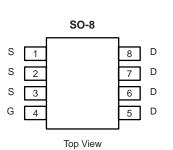
AO4292-VB Datasheet N-Channel 100 V (D-S) MOSFET

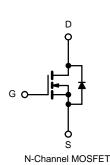
PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)			
100	0.020 at V _{GS} = 10 V	10.4	23 nC			
100	0.027 at V _{GS} = 8 V	9.5	23 110			

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Extremely Low Q_{gd} for Switching Losses
- 100 % R_g Tested
- 100 % Avalanche Tested
- Compliant to RoHS Directive 2002/95/EC







APPLICATIONS

Primary Side Switch

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	100	V	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		10.4		
Continuous Drain Current (T. 150 °C)	T _C = 70 °C	1 , —	9.1		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	8.5 ^{b, c}		
	T _A = 70 °C		7.5 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	50		
Continuous Source-Drain Diode Current	T _C = 25 °C		4.5		
Continuous Source-Drain Diode Current	T _A = 25 °C	Is	2.6 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	20		
Single Pulse Avalanche Energy	L = 0.111111	E _{AS}	20	mJ	
	T _C = 25 °C		5.9		
Maximum Dower Discinction	T _C = 70 °C		3.8	W	
Maximum Power Dissipation	T _A = 25 °C	P _D	3.1 ^{b, c}	VV	
	T _A = 70 °C	1	2 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, †}	t ≤ 10 s	R_{thJA}	33	40	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	17	21	C/ V V		

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions is 80 °C/W.



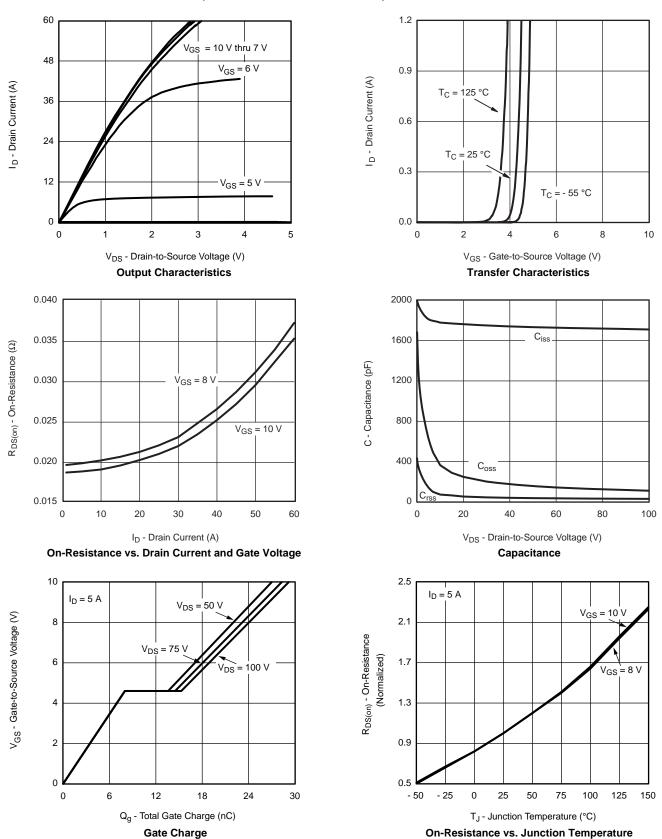
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			172		\//90	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	$I_D = 250 \mu A$		- 10		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu\text{A}$	1.5		4.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7 0 1 1/1 5 1 0 1	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
Dania Osama Os Otata Basistana	_ ` ′	V _{GS} = 10 V, I _D = 5 A		0.020		+ -	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 8 \text{ V}, I_{D} = 5 \text{ A}$		0.027		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 5 A		23		S	
Dynamic ^b	,						
Input Capacitance	C _{iss}			1735			
Output Capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		160		pF	
Reverse Transfer Capacitance	C _{rss}			37			
Total Gate Charge	Qg	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		28.5	43	nC	
				23	35		
Gate-Source Charge	Q_{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 5 \text{ A}$		8			
Gate-Drain Charge	Q _{gd}			6.5			
Gate Resistance	R _q	f = 1 MHz		0.85	1.3	Ω	
Turn-on Delay Time	t _{d(on)}			14	21		
Rise Time	t _r	V_{DD} = 50 V, R_L = 10 Ω		12	18	1	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		22	33	1	
Fall Time	t _f			6	10	1	
Turn-On Delay Time	t _{d(on)}			16	24	ns	
Rise Time	t _r	V_{DD} = 50 V, R_L = 10 Ω		12	18		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 8 \text{ V}, R_g = 1 \Omega$		20	30		
Fall Time	t _f			7	12		
Drain-Source Body Diode Characteristi	cs						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			7.7	Α	
Pulse Diode Forward Current ^a	I _{SM}				50] ^	
Body Diode Voltage	V _{SD}	I _S = 2.6 A		0.77	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			63	95	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 5 A dl/dt = 100 A/up T = 25 °C		110	165	nC	
Reverse Recovery Fall Time	t _a	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		49		20	
Reverse Recovery Rise Time	t _b	7		14		ns	

Notes:

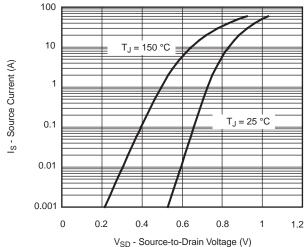
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- a. Guaranteed by design, not subject to production testing.

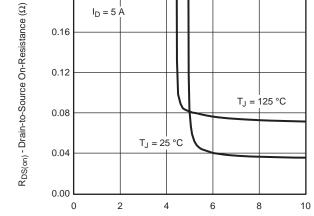
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.







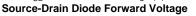




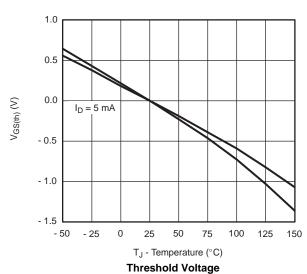
0.20

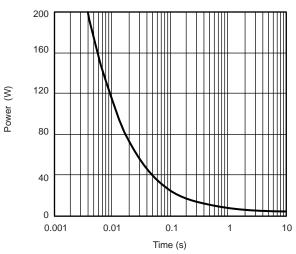
0.16

 $I_D = 5 \text{ A}$

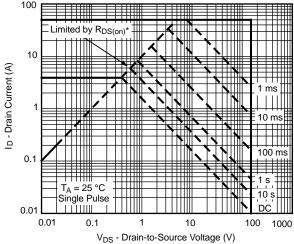








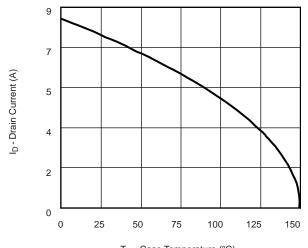
Single Pulse Power, Junction-to-Ambient



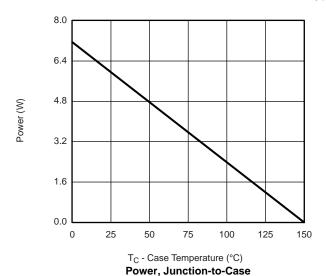
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

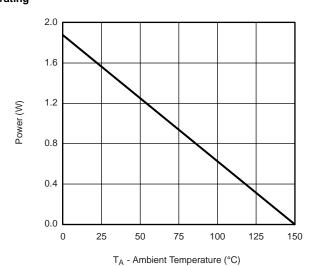
Safe Operating Area, Junction-to-Ambient





T_C - Case Temperature (°C) **Current Derating***

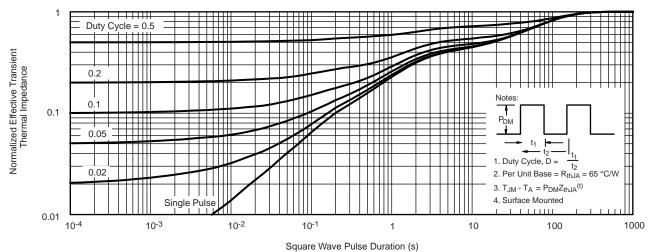




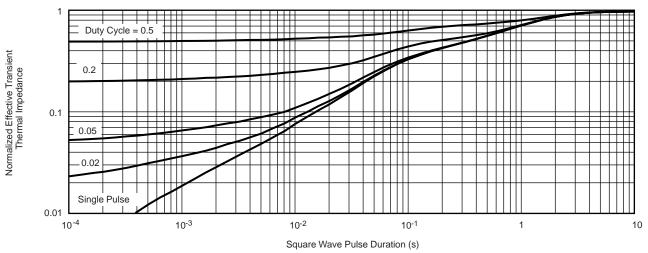
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





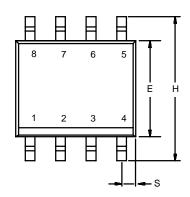
Normalized Thermal Transient Impedance, Junction-to-Ambient

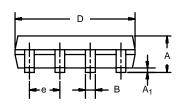


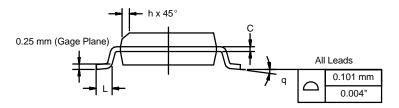
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







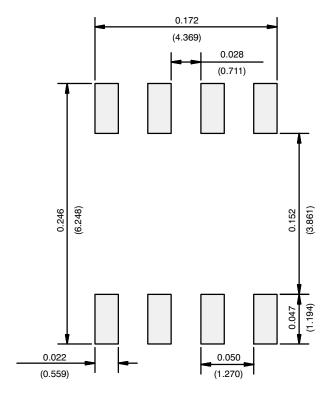
	MILLIN	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Pey 11-Sep-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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